



TECHNOLOGY DATA SHEET & SPECIFICATIONS

MODEL: 5730W2C-A

Features

- 1、Chip material: InGaN.
- 2、Emitted color: White.
- 4、Low power consumption.
- 5、High efficiency.
- 6、Versatile mounting on P.C.Board or panel.
- 7、Low current requirement.
- 8、This product don't Contained restriction Substance, compliance ROHS standard.



Usage Notes:

*Surge will damage the LED

*When using LED, it must use a protective resistor in series with DC current about 150mA

Applications

- 1、For a variety of electronic products, light sources and the state, outdoor signal instructions.
- 2、A variety of lighting project and indoor and outdoor Lighting.
- 3、Recreational facilities, a variety of media, images and performances such as art lighting.
- 4、Infrared transmitting and receiving control.

Device Selection Guide

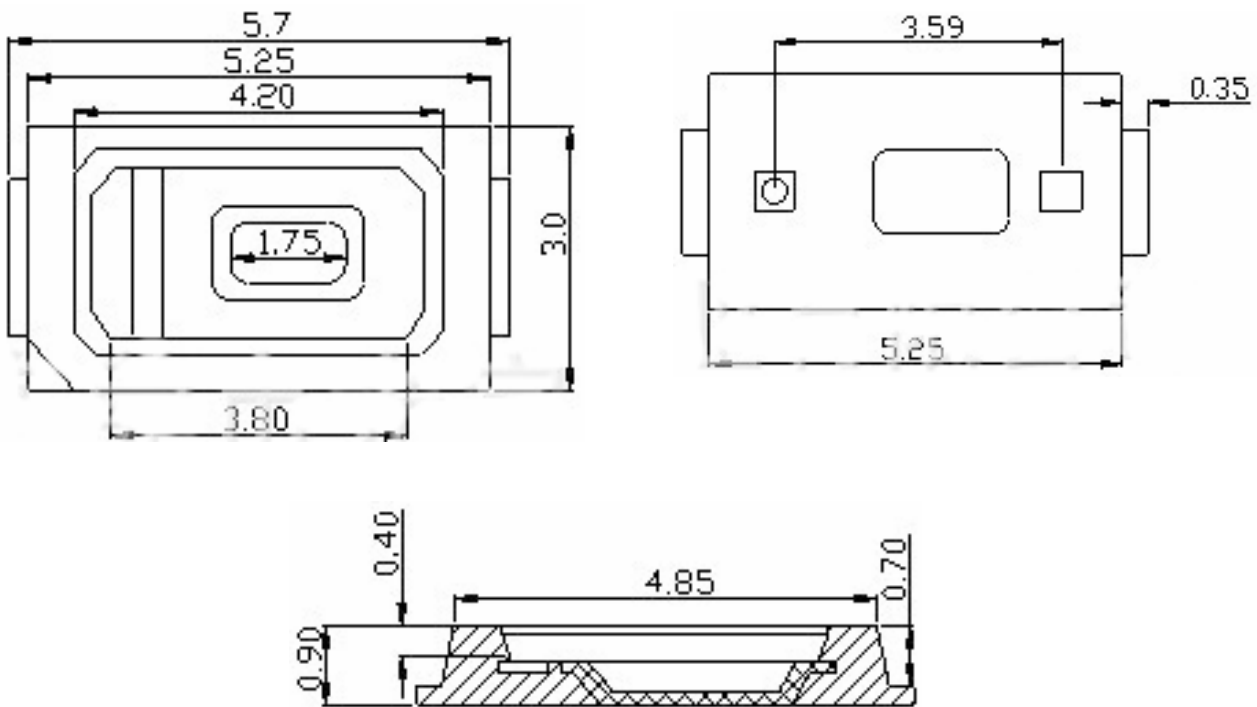
LED Part No.	Chip		Lens Color
	Material	Emitted Color	
5730W2C-A	InGaN	White	Yellow Diffused



TECHNOLOGY DATA SHEET & SPECIFICATIONS

MODEL: 5730W2C-A

Package Dimensions



Notes:

- 1、All dimension are in millimeters(inches)
- 2、Tolerance is $\pm 0.25\text{mm}(0.01)$ unless otherwise specified.
- 3、Lead spacing is measured where the leads emerge from the package.
- 4、Specifications are subject to change without notice.

Electro-Optical Characteristics (Ta=25°C)



TECHNOLOGY DATA SHEET & SPECIFICATIONS

MODEL: 5730W2C-A

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I _v	50	---	60	Lm	IF=150mA(Note1)
Viewing Angle	2θ _{1/2}	---	120	---	Deg	(Note 2)
Correlated Color Temperature	CCT	5500	---	6500	K	IF=150mA
Forward Voltage	V _F	3.0	---	3.5	V	IF=150mA
Reverse Current	I _R	---	---	10	μA	VR=5V

Note:

1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
2. θ_{1/2} is the off-axis angle at which the luminous intensity is half the axial luminous intensity.

APPLICATION NOTES:



TECHNOLOGY DATA SHEET & SPECIFICATIONS

MODEL: 5730W2C-A

1)Soldering:

① Manual soldering by soldering iron:

The use of a soldering iron of less than 25W is recommended and the temperature of the iron must be kept at no higher than 300□.

② Reflow soldering:

a. The temperature profile as shown in Fig.3 is recommended for soldering SMD LED by the reflow furnace.

b. Care must be taken that the products be handled after their temperature has dropped down to the normal room temperature after soldering.

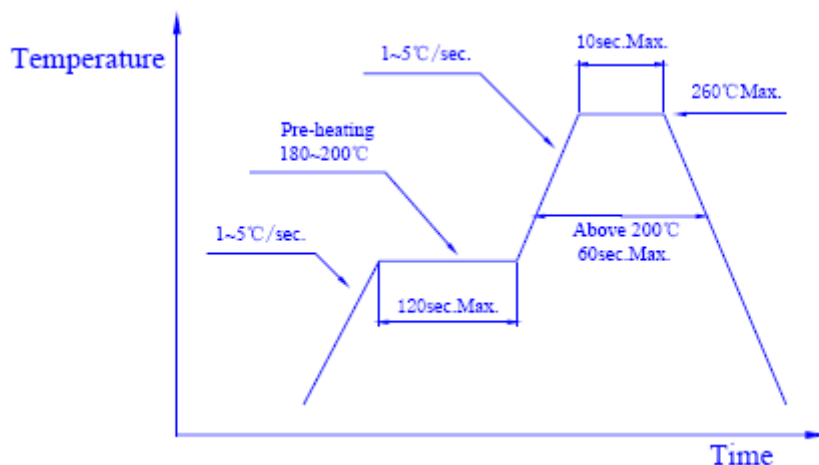


Fig.3

2)Post solder cleaning:

When cleaning after soldering is needed, the following conditions must be adhered to.

① Cleaning solvents: Freon TF or equivalent or alcohol.

② Temperature: 50□ Max.for 30 seconds or 30□ Max.for 3 minutes

③ Ultrasonic: 300W Max.



TECHNOLOGY DATA SHEET & SPECIFICATIONS

MODEL: 5730W2C-A

3) OTHERS:

- a. Care must be taken not to cause stress to the epoxy resin portion of SMD LED while it is exposed to the high temperature.
- b. Care must be taken not to the rub the epoxy resin portion of SMD LED with a hard or sharp edged article such as the sand blast and the metal hook as the epoxy resin is rather soft and liable to be damaged.